

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	IPP80N06S2-08	**Issued**	04. May 2021
MA#	MA001068260		
Package	PG-TO220-3-1	**Weight***	2039.62 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	7.124	0.35	0.35	3493	3493
leadframe	inorganic material	phosphorus	7723-14-0	0.245	0.01		120	
	non noble metal	iron	7439-89-6	0.816	0.04		400	
	non noble metal	copper	7440-50-8	815.335	39.97	40.02	399748	400268
wire	non noble metal	aluminium	7429-90-5	9.557	0.47	0.47	4686	4686
encapsulation	inorganic material	zincoxide	1314-13-2	5.896	0.29		2891	
	miscellaneous	miscellaneous	-	23.585	1.16		11563	
	plastics	epoxy resin	-	88.444	4.34		43363	
	inorganic material	silicondioxide	60676-86-0	471.702	23.13	28.92	231270	289087
leadfinish	non noble metal	tin	7440-31-5	21.462	1.05	1.05	10523	10523
plating	inorganic material	phosphorus	7723-14-0	0.001			1	
	non noble metal	nickel	7440-02-0	0.244	0.01	0.01	120	121
solder	non noble metal	tin	7440-31-5	0.099			49	
	noble metal	silver	7440-22-4	0.124	0.01		61	
	non noble metal	lead	7439-92-1	4.748	0.23	0.24	2328	2438
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		87	
	non noble metal	iron	7439-89-6	0.590	0.03		289	
	non noble metal	copper	7440-50-8	589.466	28.90	28.94	289008	289384
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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